

## SSC8L410HN6

### N-Channel Enhancement Mode MOSFET

#### ➤ Features

V <sub>DS</sub>	V <sub>GS</sub>	R <sub>DS(ON)</sub> Typ.	I <sub>D</sub>
40V	±20V	7 mΩ@10V	58A
		10 mΩ@4.5V	

#### ➤ Pin Configuration

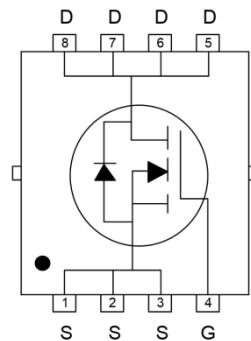


#### ➤ Description

This device is N-Channel enhancement MOSFET.

Uses SGT technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

#### PDFN5X6-8L (Top View)



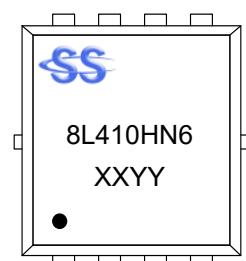
#### **Lead-Free**

**100% UIS + ΔVDS + R<sub>g</sub> Tested!**

#### ➤ Applications

- Motor Drive Control
- DCDC Conversion
- Power Supplies
- Synchronous Rectification

#### Pin Configuration



#### ➤ Ordering Information

Device	Package	Shipping
SSC8L410HN6	PDFN5X6-8L	5000/Reel

#### Marking

(XXYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
V <sub>DSS</sub>	Drain-to-Source Voltage	40	V
V <sub>GSS</sub>	Gate-to-Source Voltage	±20	V
I <sub>D</sub>	Continuous Drain Current <sup>d</sup>	T <sub>C</sub> =25°C	58
		T <sub>C</sub> =100°C	37
I <sub>DSM</sub>	Continuous Drain Current <sup>a</sup>	T <sub>A</sub> =25°C	14
		T <sub>A</sub> =70°C	11
I <sub>DM</sub>	Pulsed Drain Current <sup>b</sup>	232	A
P <sub>D</sub>	Power Dissipation <sup>c</sup>	T <sub>C</sub> =25°C	50
		T <sub>C</sub> =100°C	20
P <sub>DSM</sub>	Power Dissipation <sup>a</sup>	T <sub>A</sub> =25°C	2.7
		T <sub>A</sub> =70°C	1.7
I <sub>AS</sub>	Avalanche Current <sup>b</sup> L=0.5mH Single Pulse	14	A
E <sub>AS</sub>	Avalanche Energy <sup>b</sup> L=0.5mH Single Pulse	49	mJ
T <sub>J</sub>	Operation junction temperature	-55~150	°C
T <sub>STG</sub>	Storage temperature range	-55~150	

**➤ Thermal Resistance Ratings (T<sub>A</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Ratings	Max.	Unit
R <sub>θJA</sub>	Junction-to-Ambient Thermal Resistance <sup>a</sup>	46	60	°C/W
R <sub>θJC</sub>	Junction-to-Case Thermal Resistance	2.5	3.3	

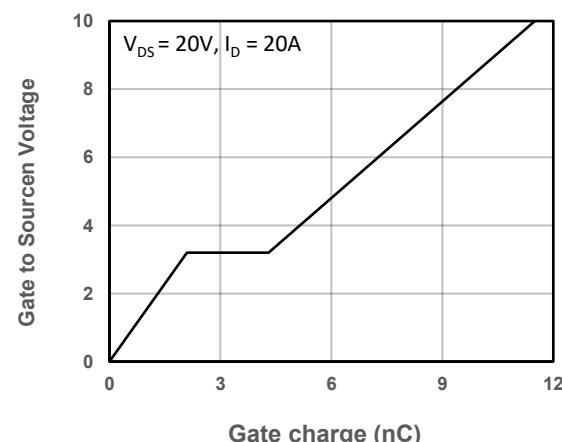
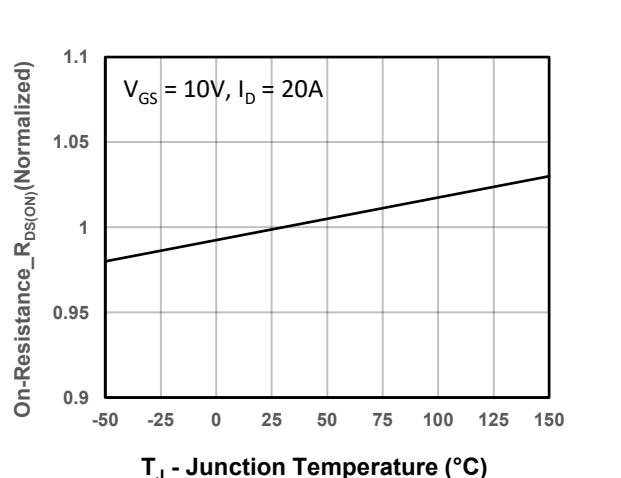
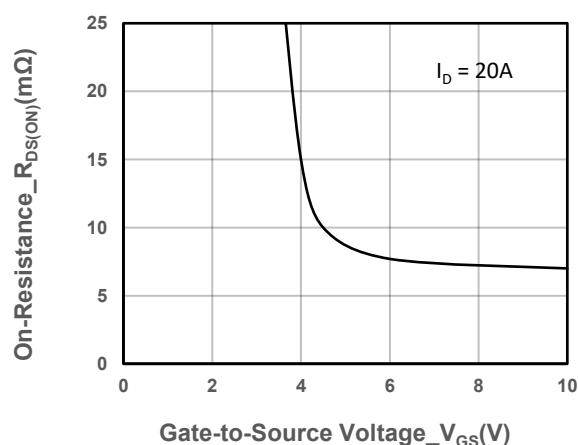
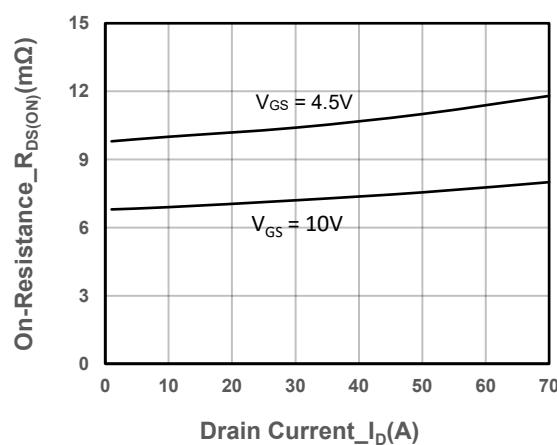
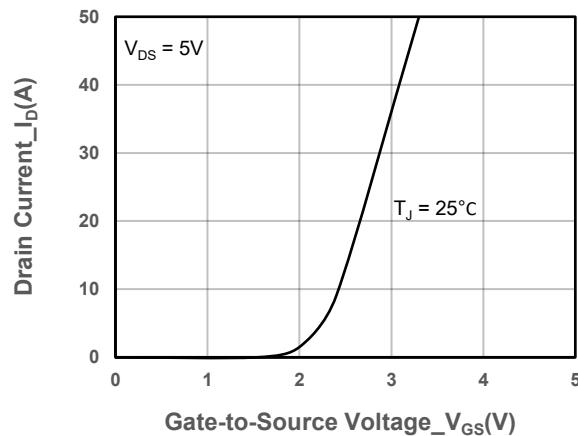
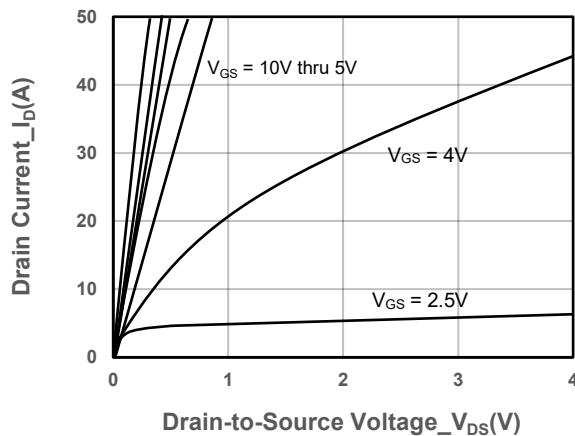
Note:

- a. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with T<sub>A</sub>=25°C. The value in any given application depends on the user's specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

➤ **Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

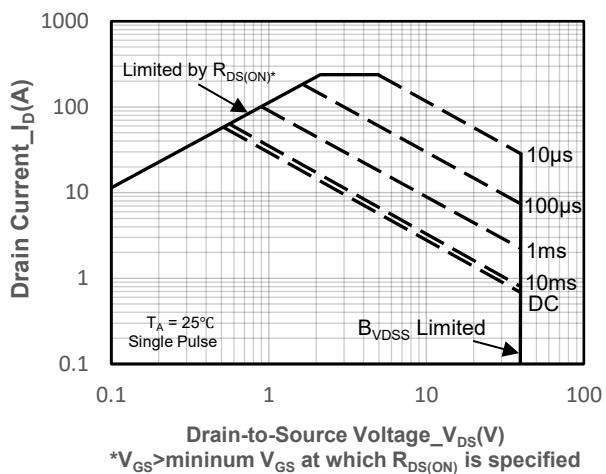
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	40			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA	1.0	1.5	2.5	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A		7	10	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A		10	14	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 10A		17		S
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 10A		0.78	1.3	V
Gate Resistance	R <sub>G</sub>	V <sub>DS</sub> = 0V, f = 1MHz		1.5		Ω
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V, f = 1MHz		650		pF
Output Capacitance	C <sub>OSS</sub>			360		
Reverse Transfer Capacitance	C <sub>RSS</sub>			18		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 20V, I <sub>D</sub> = 20A		11.5		nC
Gate to Source Charge	Q <sub>GS</sub>			2.1		
Gate to Drain Charge	Q <sub>GD</sub>			2.2		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 20V, I <sub>D</sub> = 20A, R <sub>G</sub> = 3Ω		8		ns
Rise Time	T <sub>r</sub>			6		
Turn-off Delay Time	T <sub>D(OFF)</sub>			34		
Fall Time	T <sub>f</sub>			10		
Diode Recovery Time	T <sub>rr</sub>	I <sub>F</sub> =20A, di/dt=100A/us		25		ns
Diode Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =20A, di/dt=100A/us		12		nC

➤ **Typical Performance Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**



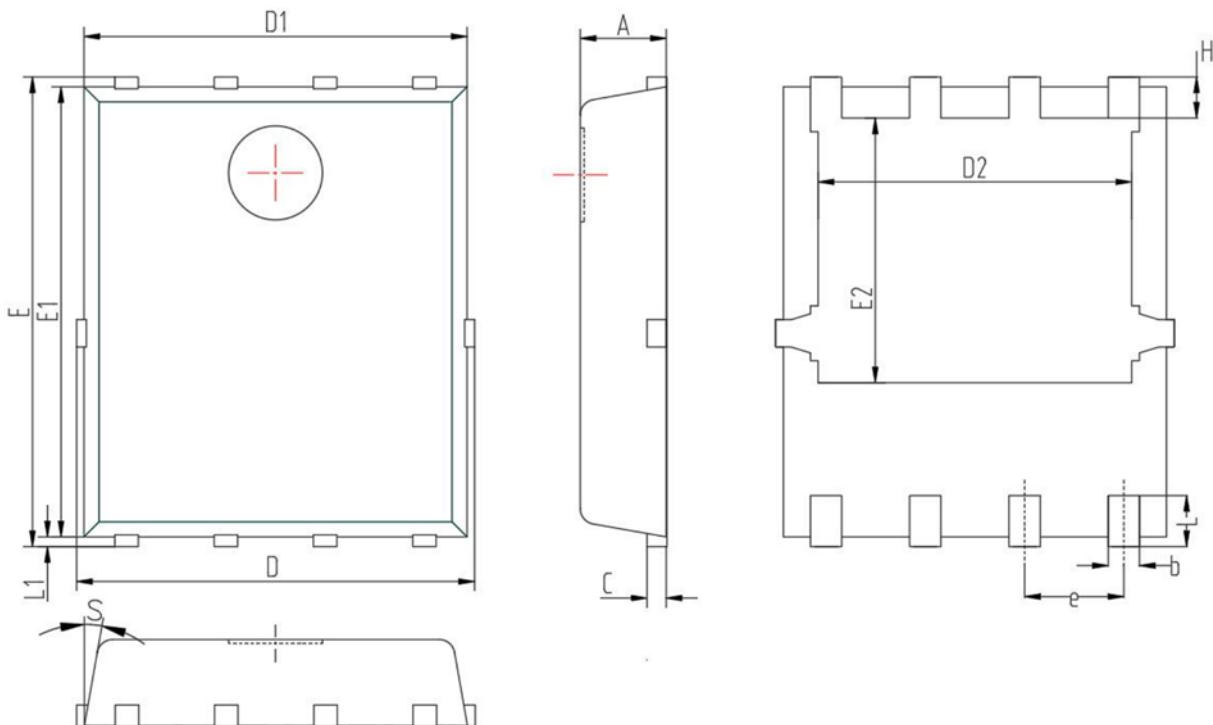
On-Resistance vs. Junction Temperature

Gate-Source Voltage vs. Gate charge



### Safe Operating Area vs. Junction-to-Ambient

➤ Package Information



Symbol	MILL IMETER		
	Min	Nom	Max
A	0.90	1.05	1.20
b	0.25	0.30	0.51
c	0.15	0.25	0.35
D	4.80	5.10	5.40
D1	4.80	5.00	5.20
D2	3.70	4.00	4.30
E	5.80	6.15	6.50
E1	5.50	5.75	5.95
E2	3.30	3.45	3.67
e	1.27BSC		
H	0.40	0.60	0.93
L	0.45	0.65	0.85
L1	0.00	0.10	0.25
S	0°	--	12°

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